

How to get Al ready? Evolution of Data Center



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since 1965

Long history of pioneering data center infrastructure technologies for mission critical applications.



Today a global organization listed on the NY Stock Exchange with a team of 31,000+ people and revenues of \$8bn (2024) from projects in 130+ countries.



Specialist in critical digital infrastructure with the most complete portfolio in power and cooling solutions wrapped in software platform and unmatched services offering.



Strong position in HPC/AI with technology partnerships and collaboration with industry leaders.



Customers include:

Alibaba, Alstom, America Movil, AT&T, China Mobile, Equinix, Ericsson, Reliance, Siemens, Telefonica, Tencent, Verizon, Vodafone



Manufacturing sites: 23



Service centers: 310+



Reach: 130+ countries

Note: All figures 2024FY.



IT Trends



VERTIV. 3

C	PUs		GPUs
Cores		res	,) [
Control	ALU	ALU	
	ALU	ALU	
Cache			

Control serves as the "coordinator" of the chip's hardware components.
Arithmetic Logic Unit (ALU) carries out the calculations (arithmetic and logical).
Cache holds frequently requested bits of data ready to be retrieved at high speed.

Function	Generalized component that handles main processing functions of a server.	Specialized component that excels at parallel computing.
Processing	Designed for serial instruction processing.	Designed for parallel instruction processing.
Design	Fewer, more powerful cores.	100s × cores of CPUs, even if less powerful individually.
Best suited for	General purpose computing applications.	High-performance computing applications.

GPUs are able to compute much faster because they were designed to compute parallel operations.

VERTIV. 4

Inside

the chip



Scenario Executing a single GPT-3 inference operation taking 350 TFLOP.

Capability

Today's processor core can typically execute 32 FP32 instructions per cycle. Processor clock rates have been stable around 3 GHz.

Total processing time

350 TFLOP 3 GHz * 32 FLOP 350 TFLOP 312 TFLOPs

NVIDIA A100 GPU has

512 tensor cores that

matrix multiplication in

a single cycle, with a

nominal capacity of

312TFLOPs.

can perform a 4×4

~1 hour

~1 second

GPUs are able to compute much faster because they were designed to compute parallel operations.

In the data center business, AI will accelerate capacity expansion.

AI workloads are incremental to conventional IT loads, not substitutive.

Total data center installed capacity (GW)





OMDIA

50kW

workload?

Conventional IT solution.



Traditional workloads were able to keep densities low by splitting loads across multiple racks.



50kW workload? Al solution.



Al workloads are driving rack density up: servers are drawing more power per rack unit, and they need to be closer together to minimize network latency and costs.

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50kW workload? Air-cooled.



Al workloads are driving rack density up: servers are drawing more power per rack unit, and they need to be closer together to minimize network latency and costs.

Traditional workloads were able to keep densities low by splitting loads across multiple racks.



80kW workload? Liquid-cooled.

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^	letworking	
	8kW	
	8kW	
	8kW	
	8kW	
	8kW	
	8kW	
6		
*		
	80kW-	•

Liquid cooling is enabling further densification with high-powered servers taking less U-space.

AI workloads are driving rack density up: servers are drawing more power per rack unit, and they need to be closer together to minimize network latency and costs.



As Al expands, rack density is on the rise with low density racks becoming the exception rather than the rule.

Number of racks installed by rack density.



NICMO

VERTIV₁₁



Coolant gets closer to the IT hardware

Liquid Cooling Direct To Chip Technologies

Single phase or Dual phase

Liquid to Liquid CDU Liquid to Air CDU



Liquid Cooling, Direct to Chip. How does it work?



VERTIV. 13

Liquid to Liquid CDU. How does it work?



Liquid to Air CDU. How does it work?



VERTIV. 15

Amount of energy feeding high-density AI chips impacts forces redesign of the entire power train of the data center.





VERTIV. 16

As GPUs become ubiquitous in data halls, they bring in challenging load profiles for supporting power infrastructure.

AI load profile



unique and very different from traditional IT

oquinment



As GPUs become ubiquitous in data halls, they bring in challenging load profiles for supporting power infrastructure.

AI load profile



Pulses result in system instabilities. UPS must be able to avoid triggering battery and generator.



NVIDIA introduced its flagship launch at GTC2024 sideby-side with Vertiv infrastructure solutions.



Computing racks

Vertiv[™] Liebert[®]

XDU 1350 coolant distribution units.

Rendering as presented by Jensen Huang at GTC2024 on 18-Mar-2024. Highlights and captions added.



Liquid cooling secondary fluid network feeding computing racks.

Networking

racks.

NVIDIA's leadership sees Vertiv as a key partner to create effective solutions in tandem with NVIDIA's growth.



Partner

BARRON'S

Nvidia CEO Says Partnership with Vertiv Will Help with Power Issue

By Tae Kim

Nvidia CEO Jensen Huang isn't too worried about the higher power draw from the company's latest Blackwell GPUs.

When asked about increasing power demands from Nvidia's latest AI GPUs during a financial analyst Q&A session at GTC Tuesday, the executive said rising requirements for absolute power, cooling, or power delivery will not be an issue.

He cited Nvidia's partnership with Vertiv, a leading provider of power and cooling infrastructure equipment, in creating effective cooling solutions for customers.

Vertiv is working side-by-side with Intel to develop power and cooling infrastructure and support its highestgrade Al solutions.



Joint development of a product strategic for Intel's growth in the AI space.



Two different liquid cooling design options: Refrigerant-to-aircooled solutions handling one rack up to 40kW.

Refrigerant-toliquid cooling system able to remove up to 160kW of heat load.

To support increasing thermal design power and heat flux for next-generation accelerators, Intel has worked with Vertiv and other ecosystem partners to enable an innovative cooling solution that will be critical in helping customers meet critical sustainability goals.

— Devdatta Kulkarni, Principal Enginee







Close partnership and collaboration with companies leading the Al revolution.

Invidia

Leader with most complete portfolio in power from

grid to chip and cooling from chip to reuse, wrapped

In monitoring and control software and AI-ready

Liebert to a NYSE-listed global organization.

Unique capabilities to meet deployment needs from

single rack to entire data center.



Global scale with resilient operational footprint, in-market expertise and field service coverage.

Your AI critical infrastructure needs are in safe hands with Vertiv. **Our offering is** unparalleled in the industry.



VERTIV

